

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Atty. Docket

NAVEED MAJID ET AL

PHA 23,843

Serial No. 09\440,595

Group Art Unit: 2811

Filed: November 15, 1999

Examiner: N. Parekh

Title: MULTIPLE SEMICONDUCTOR CHIP (MULTI-CHIP) MODULE FOR USE IN
POWER APPLICATIONS

Commissioner for Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

This amendment is in response to the Final Official Action dated July 24, 2001, in which all of the currently-pending claims were finally rejected. In order to place this application in condition for allowance or in better form for consideration on appeal (Notice of Appeal filed herewith), it is respectfully requested that this amendment be entered and that the claims be amended as follows:

IN THE CLAIMS

Kindly amend claims 1 as follows:

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1. (twice amended) A multiple semiconductor chip (multi-chip) module, comprising at least a power semiconductor chip and a